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Guidelines for Accelerated Reliability Testing of Surface Mount Solder Attachments

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Table of Contents

1.0 SCOPE 1
1.1 Purpose 1
1.2 Document Organization 1

2.0 APPLICABLE DOCUMENTS 2
2.1 IPC 2
2.2 Joint Industry Standards 2
2.3 Military 2
2.4 Other Publications 2

3.0 REQUIREMENTS
3.1 Terms and Definitions 3
3.2 Reliability Concepts and Understanding 5
3.3 Reliability Assurance 6
3.4 Damage/Failure Mechanisms 10
3.5 Application Considerations 12

4.0 SURFACE MOUNT SOLDER ATTACHMENT FATIGUE BEHAVIOR AND RELIABILITY PREDICTION 15
4.1 General Fatigue Life Models 15
4.2 Solder Joint Fatigue 15
4.3 Fatigue Behavior of Solder Joints 16
4.4 Acceleration Factors/Acceleration Transform 19
4.5 Statistical Considerations 20

5.0 DESIGN FOR SOLDER ATTACHMENT RELIABILITY 22
5.1 Primary Design Parameters 22
5.2 Secondary Design Parameters 23

6.0 MANUFACTURE/PROCESSES 24
6.1 Process Control and Verification 24
6.2 Consequences of Defects 24
6.3 Material Properties 27

7.0 ACCELERATED RELIABILITY TESTING
7.1 Reliability Program/Strategy 30
7.2 Generic Damage Mechanism Investigations 30
7.3 Thermal Cycling 30
7.4 Mechanical Cycling 32
7.5 Vibration 32
7.6 Creep Rupture Tests 33
7.7 Mechanical Shock Testing 34
7.8 Failure Criteria for Solder Joint Fatigue Tests 34
7.9 Accelerated Life Test Planning 35
7.10 Failure Mode Analysis 38
7.11 Reporting Results 41

Appendix A Step-by-Step Example 43

Appendix B References 45

Appendix C Bibliography 46

Figures

Figure 1 Flowchart for reliability 4
Figure 2 Generic reliability "bathtub" curves comparing electronic components and surface mount solder attachment 6
Figure 3 Generic cumulative failure probabilities for electronic component and surface mount solder attachment 7
Figure 4 Flow chart for surface mount solder attachment reliability assurance 8
Figure 5 Cumulative fatigue damage 10
Figure 6 SMT assembly thermo-mechanical deflections resulting from thermal gradients in thermal shock 13
Figure 7 Thermal cycle/fatigue mechanisms for solder 18
Figure 8 Shear strengths of 60:40 SnPb solder as a function of temperature and strain rate 28
Figure 9 Creep behavior of solder 34
Figure 10 Example of circuit layout 36
Figure 11 Internal lead connection schemes for odd lead numbers per side 37

Tables

Table 1 Worst-Case Use Environments for Surface Mounted Electronics and Recommended Accelerated Testing 14
Table 2 Equivalent Mean Accelerated Test Cycles 21
Table 3 Typical Values 29
Table 4 Properties of Printed Board Laminates 31
Table 1A Results of Accelerated Reliability Test 43

Guidelines for Accelerated Reliability Testing of Surface Mount Solder Attachments

1.0 SCOPE

This document provides guidelines for accelerated reliability testing of surface mount solder attachments and for evaluating and extrapolating the results of these accelerated reliability tests towards actual use environments of electronic assemblies. Background and design information is provided for an understanding of the accelerated test issues.

1.1 Purpose The purpose of accelerated reliability testing is to provide confidence that the design and the manufacturing/assembly processes are capable of meeting the intended goals of product performance. These guidelines provide adequate commonality and validity for accelerated reliability tests:

- To allow comparison of results from different test programs
- To provide the generic technical understanding of the underlying issues necessary to the design for adequate reliability
- To permit the analytical prediction of reliability based on a generic database and technical understanding
- To reduce cost and avoid time-consuming testing of every design iteration
- To establish practical alternatives to replace the excessively long test durations necessary to verify reliability of products subject to severe use environments or low failure tolerances

1.2 Document Organization This document has been organized to provide the reader with consistent information on the various aspects of reliability and identifies the parameters that need to be addressed. Each section serves a specific function in the reliability description chain. Where appropriate, references are provided as to where additional information may be obtained.

- *Section 3, "Requirements"*
  This section provides an overview of the concepts of reliability and all of the characteristics that need to be considered in the validation of a product design. Included are the definitions of the appropriate terms, as well as generic models for fatigue life and failure probability, manufacturing process flow, use environments, and testing methodology.
- *Section 4, "Surface Mount Solder Attachment Fatigue Behavior and Prediction"*
  This section deals with the fatigue life models for solder joints including their behavior when subjected to multiple cyclic loads during large temperature excursions or high frequency cycles at low temperatures. Also discussed are the acceleration factors, the acceleration transforms, and statistical considerations.
- *Section 5, "Design for Solder Joint Reliability"*
  This section details the various design parameters that have a primary influence on solder attachment fatigue reliability. All aspects of the solder joint formation are addressed including component size, lead stiffness, coefficient of thermal expansion, solder joint uniformity, as well as solder composition, grain structure and the value that conformal coating or compliant layers provide to the attachment system.
- *Section 6, "Manufacturing Processes"*
  This section provides the relationship between the assembly and attachment processes, including their control and verification, and the resultant defects or potential defects from the original processes or touch-up, rework or repair actions. Material properties of solder (including volume), components, printed boards, adhesives and conformal coatings are discussed as to their interrelationships and the impact that these characteristics have on the manufacturing processes.
- *Section 7, "Accelerated Reliability Testing"*
  This section deals with the goals of accelerated testing to produce a failure in the shortest time using techniques intended to simulate the use environment in order to establish the appropriate confidence level of product performance. Various types of stress cycling are reviewed and correlated to damage mechanisms. Also discussed is the need for developing a strategy which includes a test plan, sampling methodology, test vehicles, and failure mode analysis.
- *Appendix A, "Step-by-Step Example"*
  This section shows illustrations of applying the principles detailed in the information provided in this publication. Numerical examples are provided that highlight the relationship of the various parameters.
- *Appendix B, "References"*
  This section provides reference to published information that has a bearing on solder joint reliability and is referenced in the body of the text of this document. Details are shown as to Title, Author, and Publisher.
- *Appendix C, "Bibliography"*
  This section provides references to additional published information that could be of use to the practitioner. The references are organized into three major topics